Product/ Process Change Notification

1. PCN No.:	QPCN12023			
2. Subject:	Bonding wire material change at SOD-123			
	(Switching & Zener) SMD Diode			
3. То:	Refer to involved customer list			
4. Issued by:	Owen Wang			
5. Issue date:	3-Dec-2012			
6. Proposed first ship date for change:	4-Mar-2013			
7. Affected Product Identification				
Switching Diode & Array and Zener Diode & Array, SOD-123 package More details please see TSC involved P/N list.				
8. Change Description : (OLD Vs. NEW Comparison)				
Old:	New:			
Gold bonding wire.	Copper bonding wire.			
9. Reason for Change:				
Follow the trend of common process in the market.				
10. Anticipated Impact: (form, fit, function, quality or reliability)				
1. Product outline: No ch	ange			
5	Bonding wire material change			
•	No change			
	No change			
	o change o change			
	te code			
11.Qualification plan/result:				
Comparison report see attached				
PPAP is available on demand				
12. Sample availability Date:	3-Dec-2012			
13. Tentative implementation date:	3-Jan-2013			
14. Remarks				
15. Customer feedback required latest: (should we receive no feedback; the change will be deemed as accepted!)	3-Jan-2013			
16. Approved by:	Quayer Chen			

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Product/ Process Change Notification Customer Approval Form_QPCN12023

(Please tick the field what is valid for you!)				
We agree with this proposed change and its schedule.				
We have object	tions			
We need more	information:			
We need samp	le:			
Company:				
Name:				
Address:				
Signature:		Date:		
Signature:		Dale.		

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